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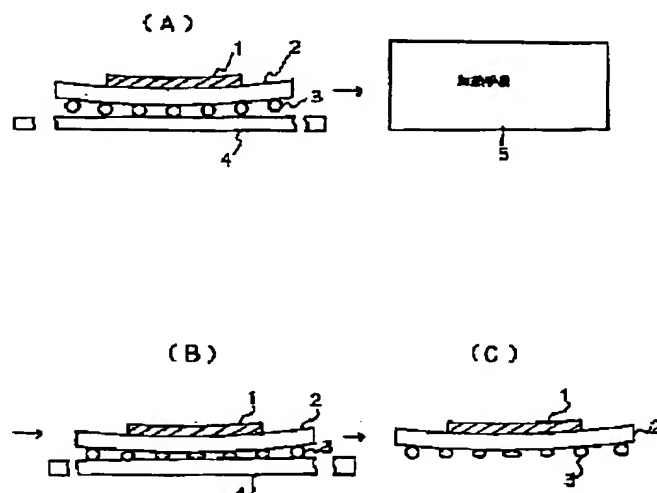
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TITLE : METHOD OF PLANARIZING  
SEMICONDUCTOR PACKAGE USING  
SOLDER BALLS AS INPUT/OUTPUT  
TERMINALS



ABSTRACT : PROBLEM TO BE SOLVED: To deform and planarize a solder ball array on a substrate by heating solder balls at specified temp. for a fixed time to melt them at a level, then cooling them, and then separating the substrate and a flat plate.

SOLUTION: A BGA package composed of a plastic body 1 and substrate 2 is laid without thermally deforming on an insol. flat plate 4 so as to have solder balls 3 directed downward and heated by a heater 5 for a specified time, so that the solder balls 3 dissolve slightly to equalize their heights due to the wt. of the package itself. The solder balls 3 inside the substrate 2 are greatly deformed due to a larger load from the package, resulting in a lower height of the balls 3. Thus the balls 3 at the right and left contour parts of the substrate 2 are taller and those inside are increasingly lower in height further inside they are.

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